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(71) Applicant (for all designated States except US): **SUMITOMO BAKELITE COMPANY LIMITED** [JP/JP];
5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo
140-0002 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **SUMIYOSHI, Takafumi** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **MIZUSHIMA, Ayako** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY

LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **OOTA, Ken** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **FUJIEDA, Yoshio** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **NIKAIDO, Hiroki** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP). **AIHARA, Takashi** [JP/JP]; c/o SUMITOMO BAKELITE COMPANY LIMITED, 5-8, Higashishinagawa 2-chome, Shinagawa-ku, Tokyo 140-0002 (JP).

(74) Agents: **ASAMURA, Kiyoshi** et al.; Room 331, New Ohtemachi Bldg., 2-1, Ohtemachi 2-chome, Chiyoda-ku, Tokyo 100-0004 (JP).

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(54) Title: EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

(57) Abstract: The present invention provides an epoxy resin composition for encapsulation of semiconductors which contains substantially neither halogen-based flame retarding agents nor antimony compounds and is excellent in moldability, flame retardance, high-temperature storage characteristics, reliability for moisture resistance, and solder cracking resistance. That is, the present invention is an epoxy resin composition for encapsulating semiconductors which contains (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a phosphazene compound as essential components, the total weight of phosphate ion and phosphite ion contained in the phosphazene compound being not more than 500 ppm. Further, the epoxy resin composition may optionally contain a flame-retarding assistant or an ion scavenger.

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